Single SPST Analog Switch

The NLAST4501 is an analog switch manufactured in sub–micron silicon–gate CMOS technology. It achieves very low R_{ON} while maintaining extremely low power dissipation. The device is a bilateral switch suitable for switching either analog or digital signals, which may vary from zero to full supply voltage.

The NLAST4501 is a low voltage, TTL (low threshold) compatible device, pin for pin compatible with the MAX4501.

The Enable pin is compatible with standard TTL level outputs when supply voltage is nominal 5.0 V. It is also over-voltage tolerant, making it a very useful logic level translator.

Features

- Guaranteed R_{ON} of 32 Ω at 5.5 V
- Low Power Dissipation: $I_{CC} = 2 \mu A$
- Low Threshold Enable pin TTL compatible at 5.0 V
- TTL version and pin for pin with NLAS4501
- Provides Voltage translation for many different voltage levels

3.3 to 5.0 V, Enable pin may go as high as +5.5 V

1.8 to 3.3 V

1.8 to 2.5 V

- Improved version of MAX4501 (at any voltage between 2 and 5.5 V)
- Chip Complexity: FETs = 11
- Pb-Free Packages are Available

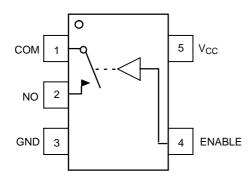


Figure 1. Pinout (Top View)



ON Semiconductor®

http://onsemi.com



SC70-5/SC-88A/SOT-353 DF SUFFIX CASE 419A



MARKING



TSOP-5 DT SUFFIX CASE 483



A3 = Specific Device Code

M = Date Code*

A = Assembly Location

Y = Year

W = Work Week

= Pb-Free Package

(Note: Microdot may be in either location)
*Date Code orientation and/or position and underbar
may vary depending upon manufacturing location.

PIN ASSIGNMENT

Pin	Function					
1	СОМ					
2	NO					
3	GND					
4	ENABLE					
5	V _{CC}					

FUNCTION TABLE

On/Off Enable Input	State of Analog Switch
L	Off
Н	On

ORDERING INFORMATION

See detailed ordering and shipping information on page 8 of this data sheet.

MAXIMUM RATINGS

	Symbol	Value	Unit	
Positive DC Supply Voltage		V _{CC}	-0.5 to +7.0	V
Digital Input Voltage (Enable)		V _{IN}	-0.5 to +7.0	V
Analog Output Voltage (V _{NO} or V _{COM})	V _{IS}	-0.5 to V_{CC} + 0.5	V
DC Current, Into or Out of Any Pin		I _{IK}	±20	mA
Storage Temperature Range	T _{STG}	-65 to +150	°C	
Lead Temperature, 1 mm from Case to	or 10 Seconds	T_L	260	°C
Junction Temperature under Bias		TJ	+150	°C
Thermal Resistance	SC70-5/SC-88A (Note 1) TSOP-5	θ_{JA}	350 230	°C/W
Power Dissipation in Still Air at 85°C	SC70-5/SC-88A TSOP-5	P _D	150 200	mW
Moisture Sensitivity		MSL	Level 1	
Flammability Rating	Oxygen Index: 30% – 35%	F _R	UL 94 V-0 @ 0.125 in	
ESD Withstand Voltage	Human Body Model (Note 2) Machine Model (Note 3) Charged Device Model (Note 4)	V _{ESD}	> 2000 > 100 N/A	V
Latchup Performance	Above V _{CC} and Below GND at 85°C (Note 5)	I _{Latchup}	±300	mA

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

- 1. Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2-ounce copper trace with no air flow.
- 2. Tested to EIA/JESD22-A114-A.
- 3. Tested to EIA/JESD22-A115-A.
- 4. Tested to JESD22-C101-A.
- 5. Tested to EIA/JESD78.

RECOMMENDED OPERATING CONDITIONS

Parameter	Symbol	Min	Max	Unit	
Positive DC Supply Voltage		V _{CC}	2.0	5.5	V
Digital Input Voltage (Enable)		V _{IN}	GND	5.5	V
Static or Dynamic Voltage Across an Off Switch		V _{IO}	GND	V _{CC}	V
Analog Input Voltage (NO, COM)		V _{IS}	GND	V _{CC}	V
Operating Temperature Range, All Package Types		T _A	- 55	+ 125	°C
Input Rise or Fall Time, (Enable Input)	$V_{cc} = 3.3 \text{ V} \pm 0.3 \text{ V} $ $V_{cc} = 5.0 \text{ V} \pm 0.5 \text{ V}$	t _r , t _f	0 0	100 20	ns/V

DEVICE JUNCTION TEMPERATURE VERSUS TIME TO 0.1% BOND FAILURES

Junction Temperature °C	Time, Hours	Time, Years
80	1,032,200	117.8
90	419,300	47.9
100	178,700	20.4
110	79,600	9.4
120	37,000	4.2
130	17,800	2.0
140	8,900	1.0

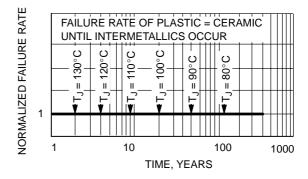


Figure 2. Failure Rate vs. Time Junction Temperature

DC CHARACTERISTICS - Digital Section (Voltages Referenced to GND)

				Guaranteed Max Limit			
Parameter	Condition	Symbol	V _{CC}	-55°C to 25°C	<85°C	<125°C	Unit
Minimum High-Level Input		V _{IH}	3.0	1.4	1.4	1.4	V
Voltage, Enable Inputs			4.5	2.0	2.0	2.0	
			5.5	2.0	2.0	2.0	
Maximum Low-Level Input		V _{IL}	3.0	0.53	0.53	0.53	V
Voltage, Enable Inputs			4.5	0.8	0.8	0.8	
			5.5	0.8	0.8	0.8	
Maximum Input Leakage Current, Enable Inputs	V _{IN} = 5.5 V or GND	I _{IN}	0 V to 5.5 V	±0.1	±1.0	±1.0	μΑ
Maximum Quiescent Supply Current (per package)	Enable and VIS = V _{CC} or GND	I _{CC}	5.5	1.0	1.0	2.0	μΑ

DC ELECTRICAL CHARACTERISTICS - Analog Section

				Guaranteed Max Limit			
Parameter	Condition	Symbol	V _{CC}	-55°C to 25°C	<85°C	<125°C	Unit
Maximum ON Resistance (Figures 8 – 12)	$\begin{aligned} &V_{IN} = V_{IH} \\ &V_{IS} = V_{CC} \text{ to GND} \\ &I_{IS}I = \leq 10.0\text{mA} \end{aligned}$	R _{ON}	3.0 4.5 5.5	45 30 25	50 35 30	55 40 35	Ω
ON Resistance Flatness	$V_{IN} = V_{IH}$ $I_{IS}I = \le 10.0 \text{ mA}$ $V_{IS} = 1 \text{ V}, 2 \text{ V}, 3.5 \text{ V}$	R _{FLAT(ON)}	4.5	4	4	5	Ω
Off Leakage Current, Pin 2 (Figure 3)	$V_{IN} = V_{IL}$ $V_{NO} = 1.0 \text{ V}, V_{COM} = 4.5 \text{ V or}$ $V_{COM} = 1.0 \text{ V and } V_{NO} 4.5 \text{ V}$	I _{NO(OFF)}	5.5	1	10	100	nA
Off Leakage Current, Pin 1 (Figure 3)	V _{IN} = V _{IL} V _{NO} = 4.5 V or 1.0 V V _{COM} = 1.0 V or 4.5 V	I _{COM(OFF)}	5.5	1	10	100	nA

AC ELECTRICAL CHARACTERISTICS (Input $t_f = t_f = 3.0 \text{ ns}$)

					G	uaran	teed I	Max Li	mit				
			Vcc	-55	°C to	25°C		< 85°	С		<125°	С	
Parameter	Test Conditions	Symbol	(V)	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
Turn-On Time	$R_L = 300 \Omega$, $C_L = 35 pF$ (Figures 4, 5, and 13)	t _{ON}	2.0 3.0 4.5 5.5		7.0 5.0 4.5 4.5	14 10 9 9			16 12 11 11			16 12 11 11	ns
Turn-Off Time	$R_L = 300 \Omega, C_L = 35 pF$ (Figures 4, 5, and 13)	t _{OFF}	2.0 3.0 4.5 5.5		11.0 7.0 5.0 5.0	22 14 10 10			24 16 12 12			24 16 12 12	ns
		•		ı	ı	Туріса	l @ 25	, VCC	C = 5.0	٧		·	
Maximum Input Capacitance, Select Input Analog I/O (switch off) Common I/O (switch off) Feedthrough (switch on)		C _{IN} C _{NO or} C _{NC} C _{COM(OFF)} C _{COM(ON)}						8 10 10 20					pF

ADDITIONAL APPLICATION CHARACTERISTICS (Voltages Referenced to GND Unless Noted)

			v _{cc}	Limit	
Parameter	Condition	Symbol	٧	25°C	Unit
Maximum On–Channel –3dB Bandwidth or Minimum Frequency Response	V_{IS} = 0 dBm V_{IS} centered between V_{CC} and GND (Figures 6 and 14)	BW	3.0 4.5 5.5	190 200 220	MHz
Maximum Feedthrough On Loss	V _{IS} = 0 dBm @ 10 kHz V _{IS} centered between V _{CC} and GND (Figure 6)	V _{ONL}	3.0 4.5 5.5	-2 -2 -2	dB
Off-Channel Isolation	$f = 100 \text{ kHz}; V_{IS} = 1 \text{ V RMS}$ V_{IS} centered between V_{CC} and GND (Figures 6 and 15)	V _{ISO}	3.0 4.5 5.5	-93	dB
Charge Injection Enable Input to Common I/O	$\begin{aligned} &V_{IS} = V_{CC} \text{ to GND, F}_{IS} = 20 \text{ kHz} \\ &t_r = t_f = 3 \text{ ns} \\ &R_{IS} = 0 \ \Omega, \ C_L = 1000 \text{ pF} \\ &Q = C_L * \Delta V_{OUT} \\ &(\text{Figures 7 and 16}) \end{aligned}$	a	3.0 5.5	1.5 3.0	pC
Total Harmonic Distortion THD + Noise	$F_{IS} = 20 \text{ Hz to 1 MHz}, \ R_L = Rgen = 600 \ \Omega, \ C_L = 50 \ pF$ $V_{IS} = 3.0 \ V_{PP} \ sine \ wave$ $V_{IS} = 5.0 \ V_{PP} \ sine \ wave$ (Figure 17)	THD	3.3 5.5	0.3 0.15	%

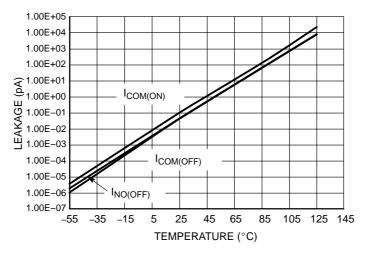
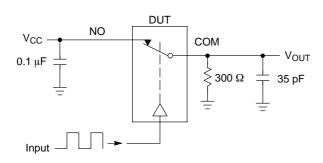


Figure 3. Switch Leakage vs. Temperature



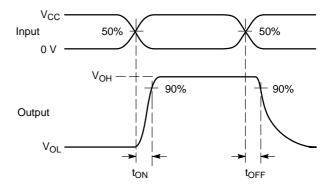
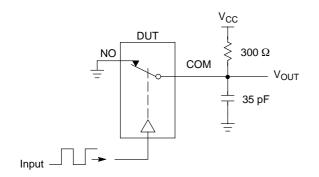


Figure 4. t_{ON}/t_{OFF}



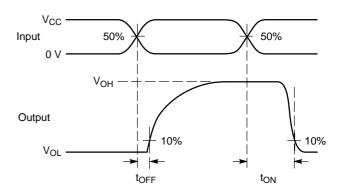
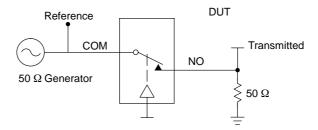


Figure 5. t_{ON}/t_{OFF}



Channel switch control/s test socket is normalized. Off isolation is measured across an off channel. On loss is the bandwidth of an On switch. $V_{\rm ISO}$, Bandwidth and $V_{\rm ONL}$ are independent of the input signal direction.

$$\begin{split} &V_{ISO} = \text{Off Channel Isolation} = 20 \text{ Log } \left(\frac{\text{VOUT}}{\text{VIN}} \right) \text{ for V}_{IN} \text{ at 100 kHz} \\ &V_{ONL} = \text{On Channel Loss} = 20 \text{ Log } \left(\frac{\text{VOUT}}{\text{VIN}} \right) \text{ for V}_{IN} \text{ at 100 kHz to 50 MHz} \end{split}$$

Bandwidth (BW) = the frequency 3 dB below V_{ONL}

Figure 6. Off Channel Isolation/On Channel Loss (BW)/Crosstalk (On Channel to Off Channel)/V_{ONL}

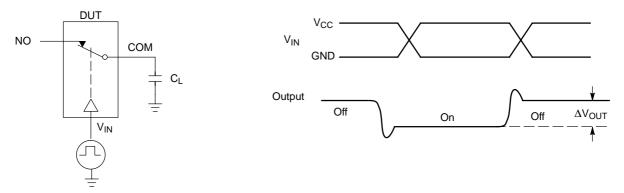


Figure 7. Charge Injection: (Q)

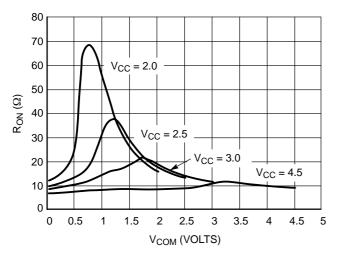


Figure 8. R_{ON} vs. V_{COM} and V_{CC} (@25°C)

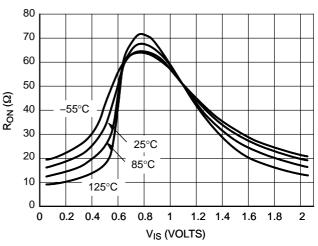


Figure 9. R_{ON} vs. V_{COM} and Temperature, V_{CC} = 2.0 V

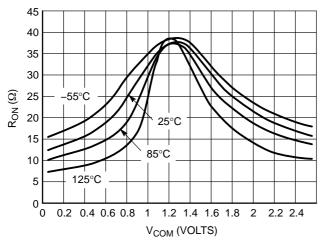


Figure 10. $R_{\mbox{\scriptsize ON}}$ vs. $V_{\mbox{\scriptsize COM}}$ and Temperature, $V_{\mbox{\scriptsize CC}}$ = 2.5 V

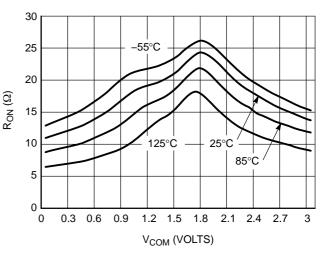


Figure 11. R_{ON} vs. V_{COM} and Temperature, V_{CC} = 3.0 V

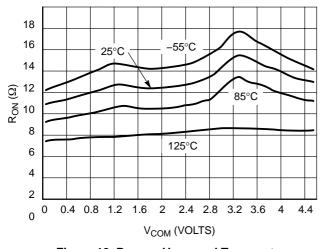


Figure 12. $R_{\mbox{\scriptsize ON}}$ vs. $V_{\mbox{\scriptsize COM}}$ and Temperature, $V_{\mbox{\scriptsize CC}} = 4.5 \mbox{ V}$

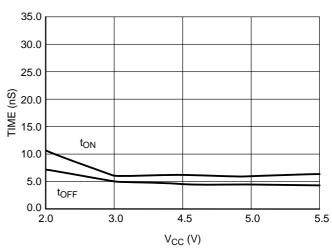


Figure 13. Switching Time vs. Supply Voltage, T = 25°C

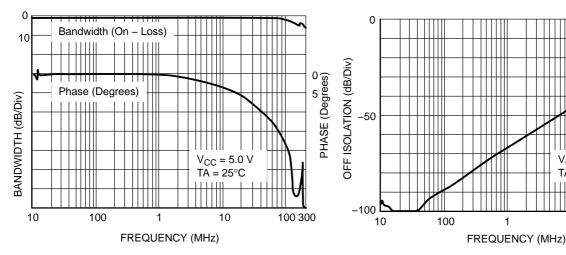


Figure 14. ON Channel Bandwidth and Phase Shift Over Frequency

Figure 15. Off Channel Isolation

 $V_{CC} = 5.0 \text{ V}$

100 300

TA = 25°C

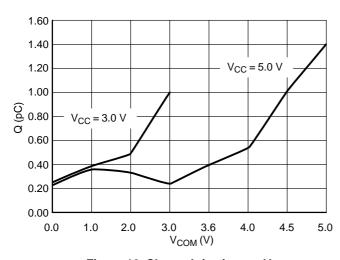


Figure 16. Charge Injection vs. V_{COM}

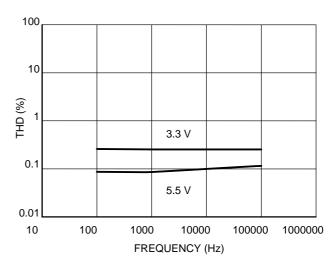


Figure 17. THD vs. Frequency

ORDERING INFORMATION

		Device	Nomenclatu	ıre			
Device	Circuit Indicator	Technology	Device Function	Package Suffix	Tape & Reel Suffix	Package	Shipping [†]
NLAST4501DFT2				5.5	T-0	SC-88A/SOT-353/ SC70	
NLAST4501DFT2G	NL	AST	4501	DF	T2	SC-88A/SOT-353/ SC70 (Pb-Free)	3000/Tape & Reel
NLAST4501DTT1						TSOP-5	
NLAST4501DTT1G				DT	T1	TSOP-5 (Pb-Free)	

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.



SC-88A (SC-70-5/SOT-353) CASE 419A-02 **ISSUE L**

DATE 17 JAN 2013



- TES:
 DIMENSIONING AND TOLERANCING
 PER ANSI Y14.5M, 1982.
 CONTROLLING DIMENSION: INCH.
 419A-01 OBSOLETE. NEW STANDARD 3.
- 419A-02.
 DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

	INC	HES	MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.071	0.087	1.80	2.20
В	0.045	0.053	1.15	1.35
C	0.031	0.043	0.80	1.10
D	0.004	0.012	0.10	0.30
G	0.026	BSC	0.65	BSC
Н		0.004		0.10
J	0.004	0.010	0.10	0.25
K	0.004	0.012	0.10	0.30
N	0.008	REF	0.20	REF
S	0.079	0.087	2.00	2.20

GENERIC MARKING DIAGRAM*



XXX = Specific Device Code

= Date Code

= Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.



0.50 0.0197 0.65 0.025 0.65 0.025 0.40 0.0157 1.9 mm 0.0748 SCALE 20:1

SOLDER FOOTPRINT

STYLE 1: PIN 1. BASE 2. EMITTER 3. BASE 4. COLLECTOR 5. COLLECTOR	STYLE 2: PIN 1. ANODE 2. EMITTER 3. BASE 4. COLLECTOR 5. CATHODE	STYLE 3: PIN 1. ANODE 1 2. N/C 3. ANODE 2 4. CATHODE 2 5. CATHODE 1	STYLE 4: PIN 1. SOURCE 1 2. DRAIN 1/2 3. SOURCE 1 4. GATE 1 5. GATE 2	STYLE 5: PIN 1. CATHODE 2. COMMON ANODE 3. CATHODE 2 4. CATHODE 3 5. CATHODE 4

5. COLLECTOR	5. CATHODE	5. CATHODE I	5. GATE 2	5. CATHODE 4
STYLE 6: PIN 1. EMITTER 2 2. BASE 2 3. EMITTER 1 4. COLLECTOR 5. COLLECTOR 2/BASE 1	STYLE 7: PIN 1. BASE 2. EMITTER 3. BASE 4. COLLECTOR 5. COLLECTOR	STYLE 8: PIN 1. CATHODE 2. COLLECTOR 3. N/C 4. BASE 5. EMITTER	STYLE 9: PIN 1. ANODE 2. CATHODE 3. ANODE 4. ANODE 5. ANODE	Note: Please refer to datasheet for style callout. If style type is not called out in the datasheet refer to the device datasheet pinout or pin assignment.

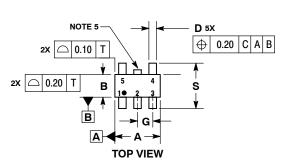
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TSOP-5 **CASE 483 ISSUE N**

DATE 12 AUG 2020









NOTES:

- DIMENSIONING AND TOLERANCING PER ASME
- CONTROLLING DIMENSION: MILLIMETERS.
 MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH
 THICKNESS. MINIMUM LEAD THICKNESS IS THE
 MINIMUM THICKNESS OF BASE MATERIAL.
- DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.15 PER SIDE. DIMENSION A. OPTIONAL CONSTRUCTION: AN ADDITIONAL
- TRIMMED LEAD IS ALLOWED IN THIS LOCATION. TRIMMED LEAD NOT TO EXTEND MORE THAN 0.2 FROM BODY.

	MILLIMETERS		
DIM	MIN	MAX	
Α	2.85	3.15	
В	1.35	1.65	
C	0.90	1.10	
D	0.25	0.50	
G	0.95 BSC		
Н	0.01	0.10	
J	0.10	0.26	
K	0.20	0.60	
М	0 °	10 °	
S	2.50	3.00	

SOLDERING FOOTPRINT*



^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*





XXX = Specific Device Code XXX = Specific Device Code

= Assembly Location = Date Code

= Year = Pb-Free Package

= Work Week W

= Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

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Europe, Middle East and Africa Technical Support:

Phone: 00421 33 790 2910

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